TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20120823000
MSP430 Cu Wirebond C035/E035 TI Taiwan TSSOP Change Notification / Sample Request

Date: 10/12/2012
To: MOUSER PCN

Dear Customer:

This is an announcement of change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. If you require samples to conduct an evaluation, please make any request within the 30 days—samples are not built ahead of the change. Please see the schedule on the following pages for availability dates. You may contact the PCN Manager or your local Field Sales Representative to acknowledge this PCN and request samples.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI’s standard process. Any negotiated alternative change requirements will be provided via the customer’s defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20120823000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
MSP430FR5729IDAR	null
MSP430L092SPW	null
MSP430L092SPWR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20120823000	**PCN Date:**	10/12/2012

Title:	MSP430 Cu Wirebond C035/E035 TI Taiwan TSSOP

Customer Contact:	PCN_ww_admin_team@list.ti.com	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	01/12/2013	**Estimated Sample Availability:**	10/12/2012

Change Type:

☐	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of Cu as an additional bond wire option for devices listed in "Product affected" section below. These parts are built in TI Wafer Fab DMOS5 and packaged in TI Taiwan in TSSOP package.

Reason for Change:

Cu bond wire option: To use wiring with enhanced mechanical and electrical properties. To align with world technology trends.

Anticipated Customer impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

None

Products affected:

MSP430L092CY
MSP430L092SPW
MSP430L092SPWR
MSP430L092SY
MSP430FR5721IDA
MSP430FR5721IDAR
MSP430FR5723IDA
MSP430FR5723IDAR
MSP430FR5725IDA
MSP430FR5725IDAR
MSP430FR5727IDA
MSP430FR5727IDAR
MSP430FR5729IDA
MSP430FR5729IDAR
MSP430FR5731IDA
MSP430FR5731IDAR
MSP430FR5733IDA
MSP430FR5733IDAR
MSP430FR5735IDA
MSP430FR5735IDAR
MSP430FR5737IDA
MSP430FR5737IDAR
MSP430FR5739IDA
MSP430FR5739IDAR
430R0009SPWR
430R0012SPWR

Qualification Data:

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device Construction Details:

	Device 1	Device 2
Device:	MSP430FR5739IDA	MSP430L092SPWR
Wafer Fab:	DMOS5	DMOS5
Wafer Technology:	1533E035.15CEW	1533C035.15CCW
Die Size:	2.08 X 2.28 mm	1.19 X 1.16 mm
Assembly Site:	TI Taiwan	TI Taiwan
Package Type/Code:	TSSOP / DA	TSSOP / PW
Package Pins:	38	14
Mold Compound:	Nitto GE1030MDP	Nitto GE1030MDP
Lead Frame:	Cu, 4115062-0004	Cu, 4042598-0005
Die Attach:	HITACHI EN-4088Z	HITACHI EN-4088Z
Moisture Level:	LEVEL2-260CG	LEVEL1-260CG

MSP430FR5739IDA Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Temperature Cycle *	-65C/150C, 1000cyc	3x77/0
Autoclave *	121C/2Atm, 96 Hours	3x 77/0
High Temp Bake *	170C, 420 Hours	3x 77/0
Manufacturability	According assembly specification	PASS

Notes:
* Moisture Preconditioning acc. MSL 2

MSP430L092SPWR Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Autoclave *	121C/2Atm, 96 Hours	3x 77/0
HAST *	85%RH, 130C, 96 Hours	3x 77/0
Manufacturability	According assembly specification	PASS

Notes:
* Moisture Preconditioning acc. MSL 1

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com